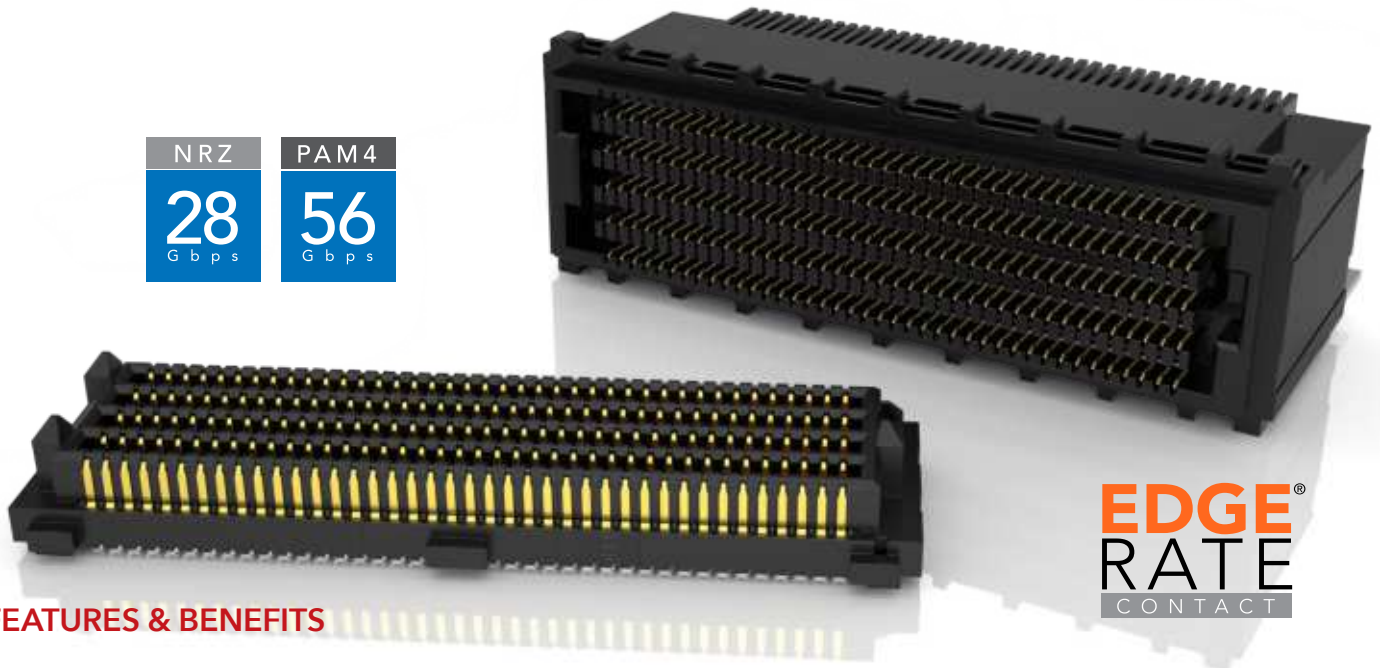
SEARAY™ .8mm

ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

(0.80 mm) .0315" PITCH

NRZ 28 Gbps

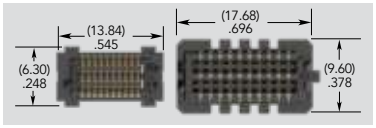
PAM4 56 Gbps



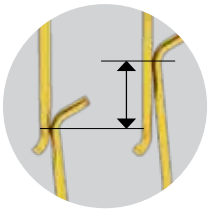
EDGE® RATE CONTACT

FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate® contact system
- Up to 500 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces
- Analog over Array™ capable
- Severe Environment Testing qualified (SEAM8/SEAF8); aligns with MIL-DTL-55302. Visit **samtec.com/set**

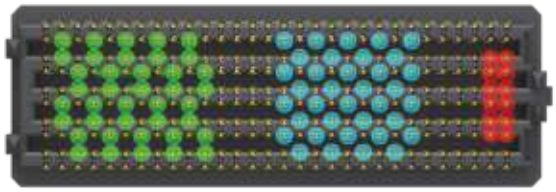


0.80 mm pitch vs. 1.27 mm pitch
(60 pins shown)



(0.95 mm) .037"
Nominal Wipe

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS (SEAF8/SEAM8)

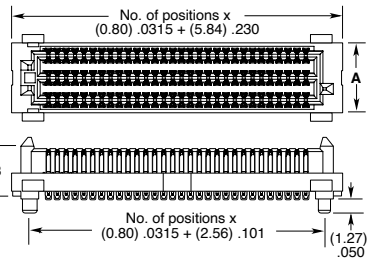
SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM8	Black LCP	Copper Alloy	Au or Sn over 50 µ" (1.27 µm) Ni	–55 °C to +125 °C	1.3 A per pin (10 adjacent pins powered)	220 VAC/311 VDC	Yes
SEAF8							
SEAF8-RA					1.1 A per pin (10 adjacent pins powered)	240 VAC/339 VDC	

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X"R
SEAM8 Terminal **SEAF8** Socket	**–10, –20, –30, –40, –50**	**–S02.0** = 2 mm Body Height (SEAM8 only) **–S05.0** = 5 mm Body Height (SEAM8 only) **–05.0** = 5 mm Body Height (SEAF8 only)	**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail	**–04** **–06** **–08** **–10**	**–3** = Lead-Free Solder Crimp	**–GP** = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	Tape & Reel is standard. Leave blank for Tape & Reel. **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

NO. OF ROWS	A
–04	(4.30) .169
–06	(6.30) .248
–08	(8.30) .327
–10	(10.30) .406

LEAD STYLE	B
-S02.0	(4.54) .179
-S05.0	(7.54) .297



SEAM8

Board Mates: SEAF8
Cable Mates: ESCA
Standoffs: JSO



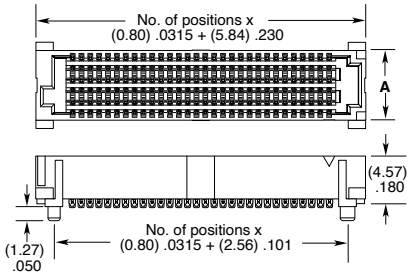
View complete specifications at: samtec.com?SEAM8

ALSO AVAILABLE
Contact Samtec
Other platings
Tin/Lead solder crimps

SEAF8

Board Mates: SEAM8
Cable Mates: ESCA
Standoffs: JSO





View complete specifications at: samtec.com?SEAF8

MATED HEIGHTS*

SEAF8 LEAD STYLE	SEAM8 LEAD STYLE	
	-S02.0	-S05.0
-05.0	(7.00) .276	(10.00) .394

*Processing conditions will affect mated height.

Notes:
Polyimide Pick & Place Pad standard without specifying –K.

Severe Environment Testing qualified; aligns with MIL-DTL-55302. Visit samtec.com/set

SEAF8	NO. PINS PER ROW	1	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
	–20, –30, –40, –50		**–S** = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on solder tail	**–04** (–50 positions only) **–08** **–10**	**–2** = Lead-Free Solder Crimp		**–GP** = Guide Post Holes	Tape & Reel is standard. Leave blank for Tape & Reel. **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

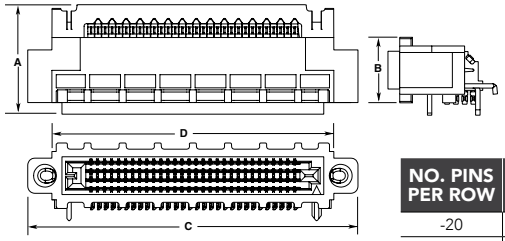
SEAF8-RA

(Right-angle)

Board Mates: SEAM8
Cable Mates: ESCA



NO. OF ROWS	A	B
–04	(12.48) .491	(7.46) .294
–08	(16.48) .649	(11.46) .451
–10	(18.48) .728	(13.46) .530



NO. PINS PER ROW	C	D
-20	(29.62) 1.166	(24.12) .950
-30	(37.62) 1.481	(32.12) 1.265
-40	(45.62) 1.796	(40.12) 1.580
-50	(53.62) 2.111	(48.12) 1.894

Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?SEAF8-RA

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